

Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

The UAD11A05L03 is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications. It is designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge(ESD), electrical fast transients(EFT), and cable discharge events(CDE).



Contact : ±10kV
Air : ±10kV

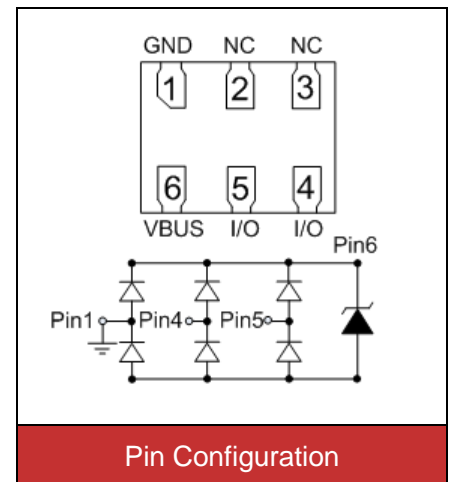


Features

- IEC61000-4-2 ESD 10KV Air, 10KV contact compliance
- DFN1109 surface mount package
- Working voltage: 5V
- Low leakage current
- Lead Free/RoHS compliant
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: 52N

Applications

- Cellular handsets & Accessories
- Cordless phones
- Personal digital assistants (PDAs)
- Notebooks & Handhelds
- Portable instrumentation
- Digital cameras
- Peripherals
- MP3 players



Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse current (tp=8/20µs)	I _{PP}	2	A
ESD voltage (Contact discharge)	V _{ESD}	±10	kV
ESD voltage (Air discharge)		±10	
Storage & operating temperature range	T _{STG} , T _J	-55~+150	°C

Electrical Characteristics ($T_J=25^{\circ}C$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				5.0	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1mA$	6.0			V
Reverse leakage current	I_R	$V_R=5V$			1.0	μA
Clamping voltage ($t_p=8/20\mu s$)	V_C	$I_{PP}=2A$		15		V
Off state junction capacitance	C_J	0Vdc, f=1MHz		0.25		pF

Typical Characteristics Curves

Figure 1. Pulse Waveform

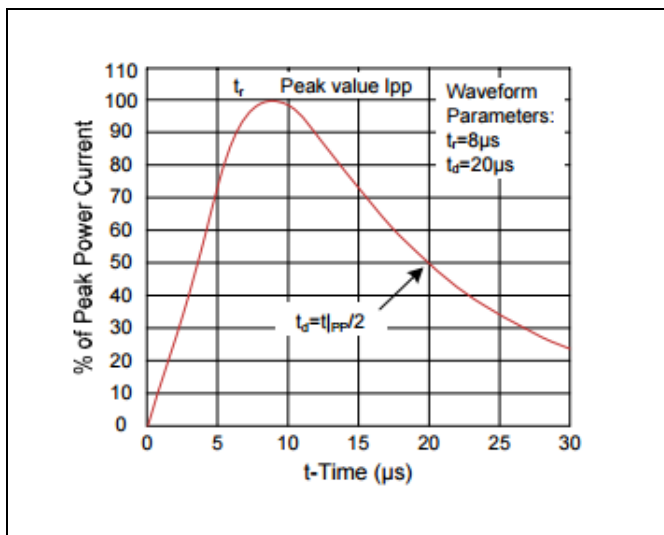


Figure 2. Clamping Voltage vs. Peak Pulse Current

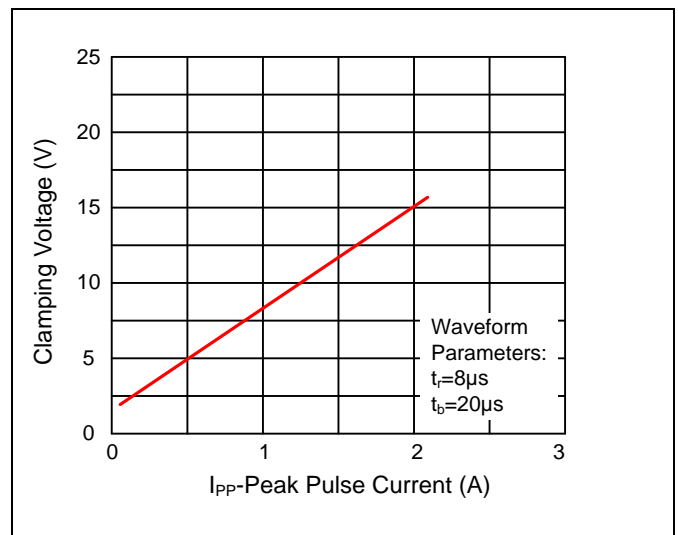


Figure 3. Capacitance vs. Reverse Voltage

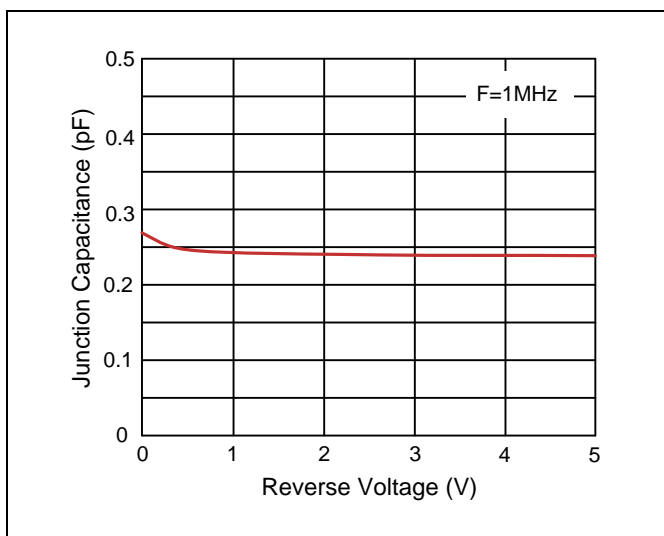
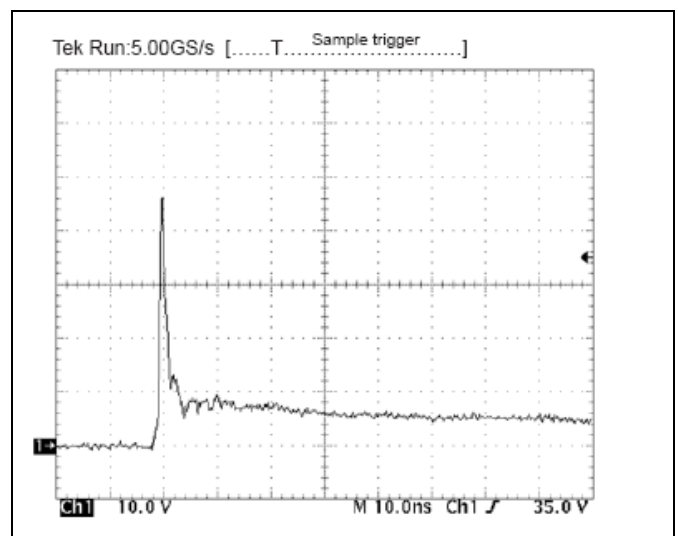
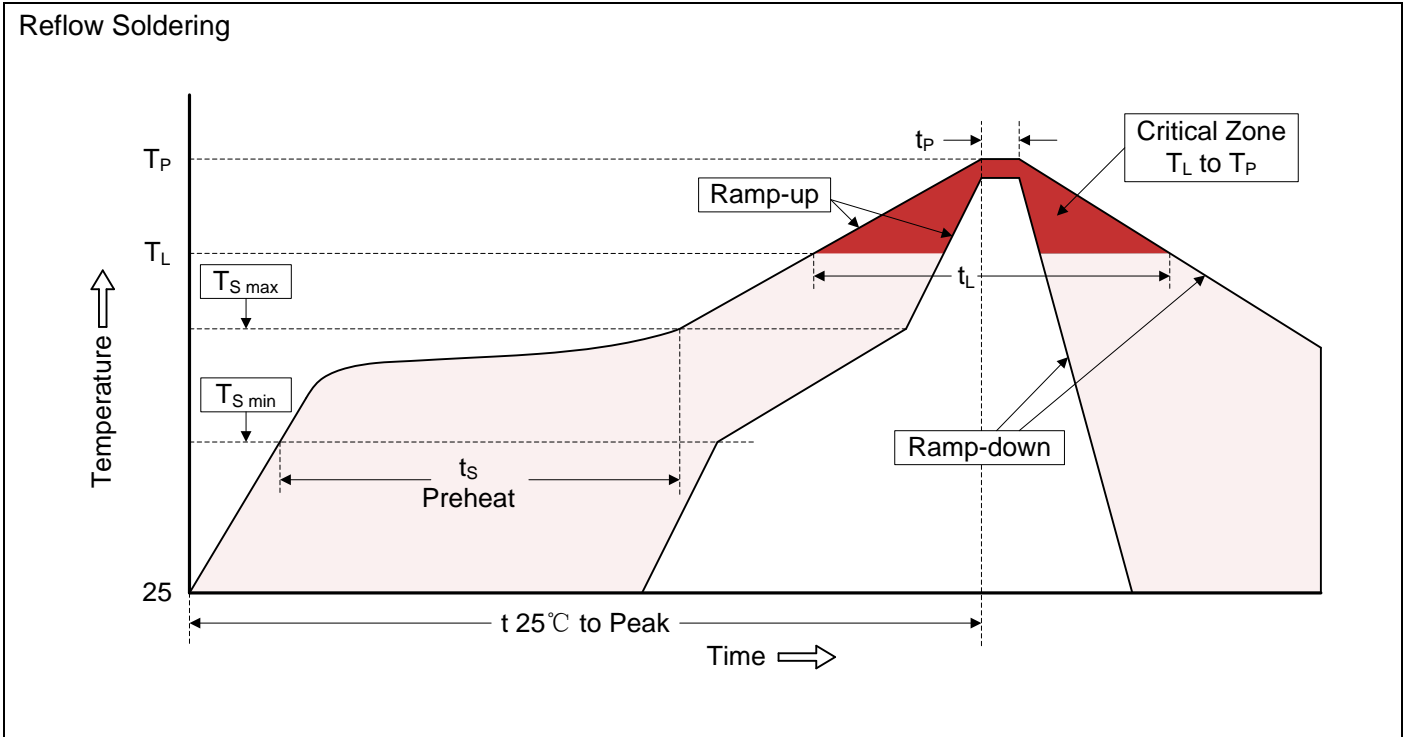


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (DFN1109)

Symbol	Dimension (mm)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.45	0.55	0.018	0.022
A1	0	0.05	0.000	0.002
b	0.15	0.25	0.006	0.010
b1	0.14REF		0.006	
c	0.10	0.20	0.004	0.008
D	1.00	1.20	0.039	0.047
e	0.40BSC		0.016BSC	
E	0.80	1.00	0.031	0.039
L	0.30	0.40	0.012	0.016
L2	0.05REF		0.002 REF	
L3	0.10REF		0.004 REF	
h	0.05	0.15	0.002	0.006

Packaging

Symbol	Dimension (mm)
W	8.00±0.10
P0	4.00±0.10
P	4.00±0.10
P2	2.00±0.05
D	1.55±0.05
D1	0.55±0.05
E	1.75±0.10
F	3.50±0.05
A0	1.02±0.05
B0	1.22±0.05
K0	0.60±0.05
t	0.25±0.05
D	Φ178.0±2.0
D2	Φ13.0±0.5
W1	8.4±1.5
Quantity: 3000PCS	